DuPont™ PlasmaSolv® EKC245™ post-etch residue remover

Made with DuPont™ HDA® hydroxylamine technology for enhanced performance

DuPont™ PlasmaSolv® EKC245™ post-etch residue remover features:
- High purity specifications for advanced wafer cleaning
- Removes residues from vias
- Cleans HBr etched polysilicon
- Removes residues after metal etch
- Operates below flashpoint
- Low evaporation rate at operating temperatures
- Does not require ultrasonics
- Rinses in water
- Compatible with automatic equipment

- Great device reliability and product yields
- Lowers via contact resistance
- Maintains gate oxide integrity
- Improves contact between metal layers
- Combines wet chemical processes
- Provides a safe chemical process
- Extends bath life, reduces air emissions, lowers factory operating cost
- Reduces equipment requirements
- Reduces cost of ownership by simplifying process
- Offers flexibility in process

0.5µm Metal Lines
Before Clean
After Clean
Ox/Ti/AlCu/TiN
20 min. @ 65°C

0.5µm Via
Before Clean
After Clean
AlSiCu/TiN/TEOS
20 min. @ 65°C

EKC245™ U.S. and Foreign Patents Pending
For more information on DuPont™ PlasmaSolv® EKC245™ post-etch residue remover or other DuPont EKC Technology products, please contact your local representative, or visit our website:

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Caution: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see “DuPont Medical Caution Statement: H-51459 or H-50102-2

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